2SC3829

Silicon NPN epitaxial planar type

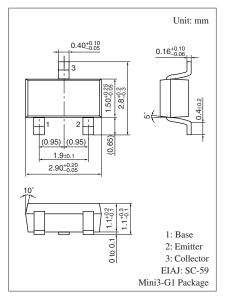
For UHF band low-noise amplification

■ Features

- Low noise figure NF
- High gain
- High forward transfer gain $|S_{21e}|^2$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V _{CBO} | 15 | V | |
| Collector-emitter voltage (Base open) | V _{CEO} | 10 | V | |
| Emitter-base voltage (Collector open) | V_{EBO} | 2 | V | |
| Collector current | I_C | 80 | mA | |
| Collector power dissipation | P _C | 200 | mW | |
| Junction temperature | T_{j} | 150 | °C | |
| Storage temperature | T_{stg} | -55 to +150 | °C | |

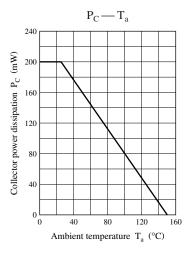


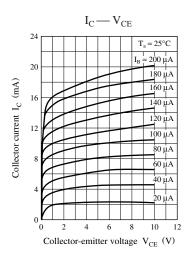
Marking Symbol: 3M

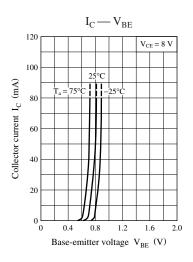
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

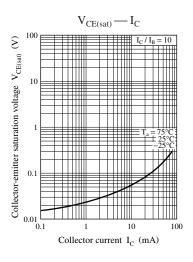
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------------------|--|------|------|-----|------|
| Collector-base voltage (Emitter open) | V _{CBO} | $I_{\rm C} = 10 \mu{\rm A}, I_{\rm E} = 0$ | 15 | | | V |
| Collector-emitter voltage (Base open) | V _{CEO} | $I_C = 100 \ \mu A, I_B = 0$ | 10 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 10 \text{ V}, I_{E} = 0$ | | | 1 | μΑ |
| Emitter-base cutoff current (Collector open) | I_{EBO} | $V_{EB} = 2 \text{ V}, I_{C} = 0$ | | | 1 | μΑ |
| Forward current transfer ratio | h _{FE} | $V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}$ | 50 | 150 | 300 | _ |
| Transition frequency | f_T | $V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$ | 5 | 6 | | GHz |
| Collector output capacitance | C _{ob} | $V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 0.7 | 1.2 | pF |
| (Common base, input open circuited) | | | | | | |
| Forward transfer gain | S _{21e} 2 | $V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$ | 10.0 | 13.5 | | dB |
| Maximum unilateral power gain | G_{UM} | $V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$ | | 15 | | dB |
| Noise figure | NF | $V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$ | | | 2 | dB |

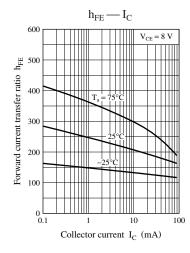
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

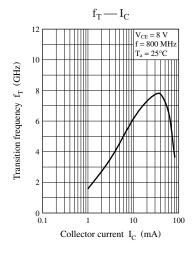


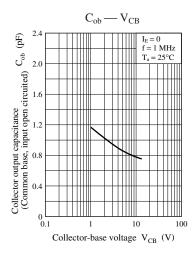


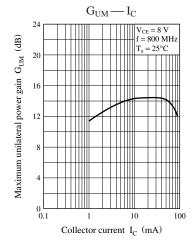


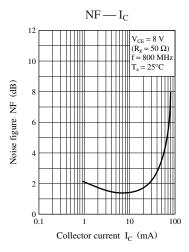












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